

Listing of Claims

The following listing of claims will replace all prior versions, and listings, of claims in the subject application:

1. (original) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer, wherein the amount of the adhesive ranges from 0.05 g/m² to 1.5 g/m², and the bonding strength between the porous resin layer and the porous fiber layer ranges from 0.8 N/m to 50.0 N/m.
2. (withdrawn) A heat-sensitive stencil sheet according to claim 1, wherein the adhesive is a primarily urethane adhesive of moisture-curable type.
3. (original) A heat-sensitive stencil sheet according to claim 1 or claim 2, wherein the adhesive is a primarily adhesive of ionizing radiation-curable type.
4. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 0.5 g/m² to 10.0 g/m² by dry basis.
5. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 1.0 g/m² to 5.0 g/m² by dry basis.
6. (original) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin

layer is a foamy film formed by applying a fluid containing an resin emulsion of water in oil type onto a thermoplastic film and drying it.

7. (original) A heat-sensitive stencil sheet according to claim 1, wherein amount of the porous fiber layer ranges from 1.0 g/m² to 15.0 g/m².

8. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous fiber layer ranges from 3.0 g/m² to 10.0 g/m².

9. (withdrawn) A method for fabricating a heat-sensitive stencil sheet according to claim 1 comprising the steps of; applying a coating liquid to one side of a thermoplastic film to form a porous resin layer attached to the thermoplastic film; and after at least the outermost surface of the porous resin layer is dried and cured, bonding the porous resin layer to a porous fiber layer coated with a adhesive.

10. (withdrawn) A thermal stencil printing apparatus loaded with a perforated heat-sensitive stencil master produced from a heat-sensitive stencil sheet, wherein the heat-sensitive stencil sheet is one as claimed in claim 1.

11. (new) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells.

12. (new) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin

layer has an assembly of cells in a honey combed structure.

13. (new) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin layer includes an assembly of granular-shaped or fabric-shaped resin segments coupled together.

14. (new) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous resin layer have an average diameter in a range of 5 μm to 20 μm .

15. (new) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous resin layer are connected in a depth direction and to a lesser degree in a transverse direction, so that sideward deviated penetration of ink in the stencil sheet is decreased.

16. (new) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer have an average diameter in a range of 25 μm to 60 μm .